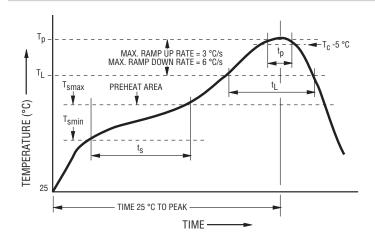


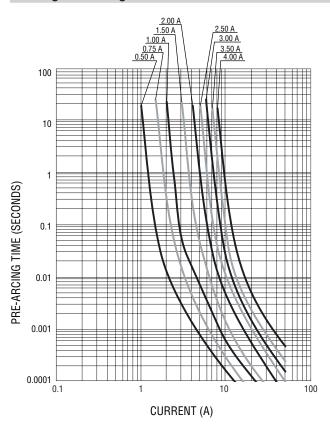
## **Solder Reflow Recommendations**



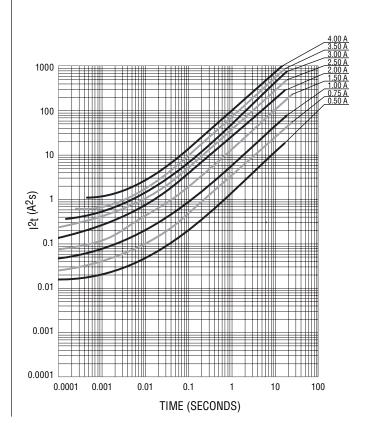
Pb-Free Assembly
150 °C 200 °C
60~120 seconds
3 °C / second max.
217 °C 60~150 seconds
260 °C
30 seconds*
6 °C / second max.
8 minutes max.

<sup>\*</sup> Tolerance for peak profile temperature (Tp ) is defined as a supplier minimum and a user maximum.

## **Average Pre-Arcing Time vs. Current Curves**



## Average I2t vs. t Curves



Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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Tape Dimensions	SF-0603HlxxxF Series per EIA 481-2
w	$\frac{8.10 \pm 0.20}{(.319 \pm .008)}$
$\overline{P_0}$	$\frac{4.0 \pm 0.10}{(.157 \pm .004)}$
P <sub>1</sub>	$\frac{4.0 \pm 0.10}{(.157 \pm .004)}$
P <sub>2</sub>	$\frac{2.0 \pm 0.05}{(.079 \pm .002)}$
A <sub>0</sub>	$\frac{1.00 \pm 0.10}{(.039 \pm .004)}$
B <sub>0</sub>	$\frac{1.80 \pm 0.10}{(.071 \pm .004)}$
F	$\frac{3.50 \pm 0.05}{(.138 \pm .002)}$
E <sub>1</sub>	$\frac{1.75 \pm 0.10}{(.069 \pm .004)}$
$D_0$	$\frac{1.55 + 0.05}{(.061 + .002)}$

